

HiRel NPN Silicon RF Transistor

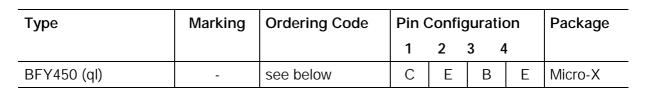
- HiRel Discrete and Microwave Semiconductor
- For Medium Power Amplifiers
- Compression Point P-1dB = 19dBm 1.8 GHz
 Max. Available Gain Gma = 16dB at 1.8 GHz
- Hermetically sealed microwave package
- Transition Frequency $f_T = 20 \text{ GHz}$
- SIEGET 25-Line Infineon Technologies Grounded Emitter Transistor-25 GHz f_T-Line



ESA/SCC Detail Spec. No.: 5611/008

Type Variant No. 03



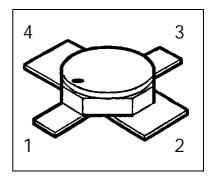


(ql) Quality Level: P: Professional Quality, Ordering Code: Q62702F1663

H: High Rel Quality,S: Space Quality,Ordering Code: on requeston request

ES: ESA Space Quality, Ordering Code: Q62702F1708

(see order instructions for ordering example)





Maximum Ratings

Parameter	Symbol	Values	Unit			
Collector-emitter voltage	V _{CEO}	4.5	V			
Collector-base voltage	V _{CBO}	15	V			
Emitter-base voltage	V _{EBO}	1.5	V			
Collector current	I _C	100	mA			
Base current	I _B	10	mA			
Total power dissipation, $T_S \le 110^{\circ}C^{-1), 2)}$	P _{tot}	450	mW			
Junction temperature	T _j	175	°C			
Operating temperature range	T _{op}	-65+175	°C			
Storage temperature range	T _{stg}	-65+175	°C			
Thermal Resistance						
Junction-soldering point 2)	R _{th JS}	< 145	K/W			

- Notes.: 1) At $T_S = +110$ °C. For $T_S > +110$ °C derating is required.
- 2) T_S is measured on the collector lead at the soldering point to the pcb.

Electrical Characteristics

at T_A=25°C; unless otherwise specified

Parameter	Symbol	Values			Unit		
		min.	typ.	max.			
DC Characteristics							
Collector-base cutoff current	I _{CBO}	-	-	100	nA		
$V_{CB} = 5 V$, $I_E = 0$							
Collector-emitter cutoff current 1.)	I _{CEX}	-	-	200	μA		
$V_{CE} = 4.5 \text{ V}, I_B = 1.0 \mu A$				(t.b.d.)			
Emitter-base cuttoff current	I _{EBO}	-	-	50	μΑ		
$V_{EB} = 1.5 \text{ V}, I_{C} = 0$							
DC current gain	h _{FE}	50	90	150	-		
$I_C = 20 \text{ mA}, V_{CE} = 1 \text{ V}$							

Notes:

1.) This Test assures V(BR)CE0 > 4.5V



Electrical Characteristics (continued)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics		•	•	•	
Transition frequency	f _T				GHz
$I_C = 90mA$, $V_{CE} = 3 V$, $f = 1.0 GHz$		18	22	-	
$I_C = 90mA$, $V_{CE} = 3 V$, $f = 2.0 GHz$		-	17	-	
Collector-base capacitance	ССВ	-	0.42	0.9	pF
$V_{CB} = 2 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C _{CE}	-	1.27	2.6	pF
$V_{CE} = 2 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Emitter-base capacitance	C _{EB}	-	2.0	3	pF
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 MHz$					
Noise Figure	F	-	1.25	2.0	dB
$I_C = 10 \text{ mA}, V_{CE} = 2 \text{ V}, f = 1.8 \text{ GHz},$					
$Z_S = Z_{sopt}$					
Insertion power gain	$\left S_{21\mathrm{e}}\right ^2$	8.0	12	-	dB
$I_C = 50 \text{ mA}, V_{CE} = 2 \text{ V}, f = 1.8 \text{ GHz}$					
$Z_S = Z_L = 50 \Omega$					
Power gain	Gma ^{1.)}	-	16.0	-	dB
$I_C = 50 \text{ mA}, V_{CE} = 2 \text{ V}, f = 1.8 \text{ GHz}$					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					
1dB Compression point	P _{-1dB}	-	19	-	dBm
$I_C = 50 \text{ mA}, V_{CE} = 2 \text{ V}, f = 1.8 \text{ GHz}$					
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$					

Notes.:

1)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....

BFY450 (ql)

(ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1708

BFY450 ES

For BFY450 in ESA Space Quality Level

Further Informations:

See our WWW-Pages:

Discrete and RF-Semiconductors (Small Signal Semiconductors)
 www.infineon.com/products/discrete/hirel.htm

 HiRel Discrete and Microwave Semiconductors www.infineon.com/products/discrete/hirel.htm

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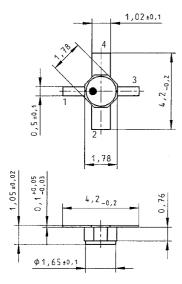
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Micro-X Package



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